



AF/FFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Joseph M. Steigerwald

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Art Unit: 2815

Serial No.: 10/722,801

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Examiner: Sheila V. Clark

Filed: November 26, 2003

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Atty Docket: ITL.0947US
P15971

For: Electrochemically Polishing Conductive
Films on Semiconductor Wafers

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Assignee: Intel Corporation

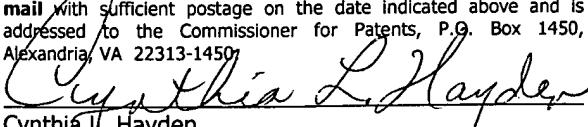
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Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the final rejection mailed April 19, 2005, please amend the above-referenced patent application as follows:

Date of Deposit: <u>May 4, 2005</u>
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Cynthia L. Hayden